

METHOD TO REDUCE NUMBER OF WIRE-BOND LOOP HEIGHTS VERSUS
THE TOTAL QUANTITY OF POWER AND SIGNAL RINGS

ABSTRACT OF THE DISCLOSURES

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A method for reducing the number of wire-bond loop heights which are required in comparison with a total quantity of power and signal rings employed in low profile wire-bond integrated circuit packages. There are also provided low profile wire-bond packages which are produced in accordance with the method pursuant to the invention.